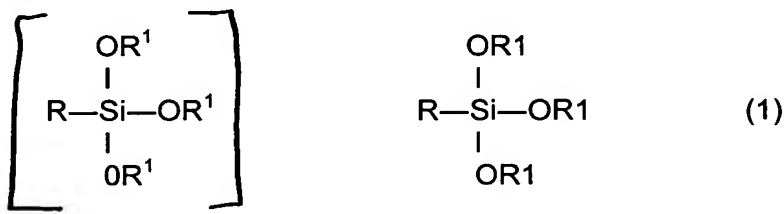


Amendments to the Claims:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

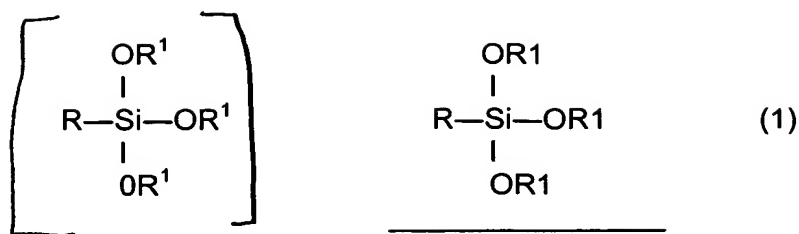
Listing of Claims:

1. (Currently Amended): A semiconductor device in which, at least, part of the semiconductor is coated or sealed with a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin ~~(a), a(b) a reaction product (b) of the reaction of an organosilicon compound, represented by the general formula (1)~~



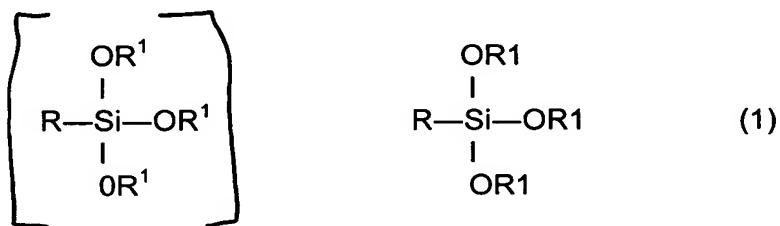
(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R¹ is a methyl or ethyl group), with water in the presence of the epoxy resin (a), and(c) a curing agent (e), and (d) an inorganic filler, as essential components; and said composition is in a liquid form at a room temperature (25°C), ~~and inorganic filler as essential components(25°C).~~

2. (Currently Amended): A semiconductor device in which a semiconductor chip and a lead frame are bonded together using a die bonding material containing a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin ~~(a), a product (b) of the reaction, (b) a reaction product of an organosilicon compound, represented by the general formula (1)~~



(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R1 is a methyl or ethyl group), with water in the presence of the epoxy resin (a), and (c) a curing agent (e), and (d) metallic powder, as essential components; and said composition is in a liquid form at a room temperature (25°C), ~~and metallic powder as essential components.~~

3. (Currently Amended): A semiconductor device in which the semiconductor and a wiring board are mounted using a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin, (a), a product (b) of the reaction (b) a reaction product of an organosilicon compound, represented by the general formula (1)



(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R1 is a methyl or ethyl group), with water in the presence of the epoxy resin, (a), and (c) a curing agent, (e) as essential components and (d) conductive metallic powder, as essential components; and said composition is in a liquid form at a room temperature (25°C), ~~and conductive metallic powder as essential components.~~